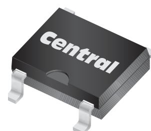
Material Composition Specification

LPDIP Case



Device average mass . . . . 89.9 mg

Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	3.23%	2.9	Si	7440-21-3	3.23%	2.9	32,258
bond wire	copper	0.42%	0.38	Cu	7440-50-8	0.42%	0.38	4,227
leadframe	Cu alloy	44.46%	39.97	Cu	7440-50-8	44.39%	39.91	443,938
				Fe	7439-89-6	0.07%	0.06	667
die attach	high temperature solder paste	2.04%	1.837	Pb	7439-92-1	1.89%	1.7	18,910
				Sn	7440-31-5	0.10%	0.091	1,012
				Ag	7440-22-4	0.05%	0.046	512
encapsulation*	EMC GREEN	49.35%	44.363	silica	60676-86-0	38%	34.16	379,978
				epoxy resin	29690-82-2	4.94%	4.44	49,388
				phenol resin	9003-35-4	4.78%	4.3	47,831
				carbon black	1333-86-4	0.15%	0.133	1,479
				metal hydroxide	1309-42-8	1.48%	1.33	14,794
plating	matte tin	0.5%	0.45	Sn	7440-31-5	0.5%	0.45	5,006

*EMC GREEN molding compound is Halogen Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.